

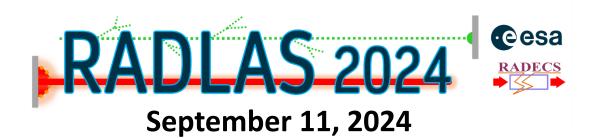


# Comparison between Laser and Heavy Ions test results from NSSC

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## **Outline**

- General Background –Pulsed Laser SEE
- Pulsed Laser Quantitative SEE Testing
   Technique
- Quantitative Calibration
- Sensitive Region Location
- Review and Prospect



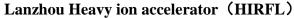
## **General Background**

For device manufacture, spacecraft electronic instrument development and the mechanism investigation, the SEE sensitivity of Devices have to be evaluated. Usually by heavy ion accelerator, BUT:

- Time and money consuming (To be booked in advance)
- Need radioprotection-Vacuum
- Not adequate to evaluate sensitivity for sensitive region mapping
- Identical LET not available for heavy ions penetration depth issue etc.
   So pulsed laser could be a complementary tool to overcome the above issues. AND:
- SEE sensitive region mapping need visible and accurate location
- SEE fundamental research need the spatial, temporal and original characterization
- SEE pre-evaluation of various configurations/complex components need relatively universal calibration between laser and heavy ion



# **Single Event Effects Facility**



NSSC 50 MeV proton accelerator

NSSC pulsed laser facility







Heavy ion

Proton

Laser

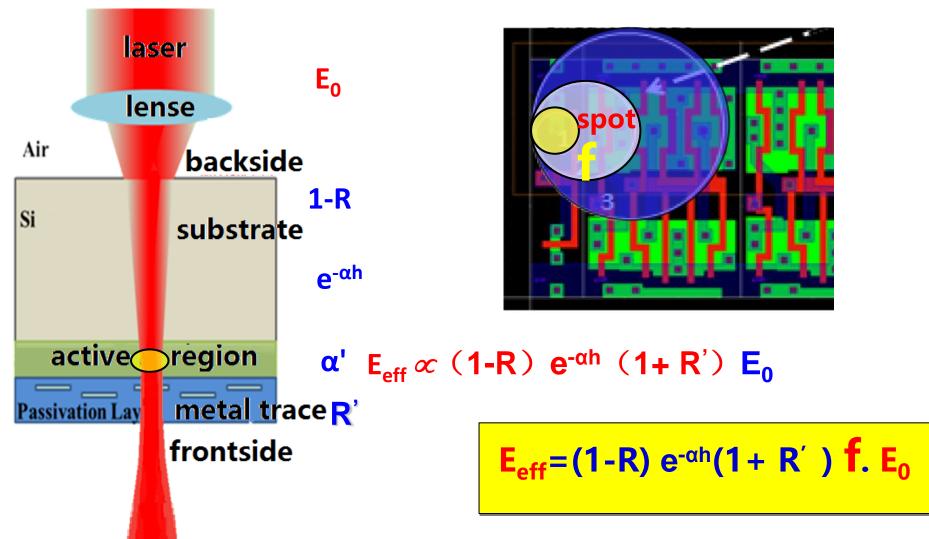


## **▶** Pulsed Laser Test Conditions

Facility		DUT	
Wavelength	280-2600 nm	Sample Preparation	Chip on Board repackaging; SIP SOP plastic packages; Flip chipped device; Ceramic packages possible
Pulse Width	35 fs/15 ps	Reflection on the substrate surface	R=0.38~0.40
Pulsed Laser Energy E <sub>eff</sub>	Measured value	silicon substrate thickness h	Measured value
Penetration Depth	>1000 μm	absorption coefficient α	Measured value
Spot size Diameter	<2 μm	Reflection on the metal layer interface R'	Measured value

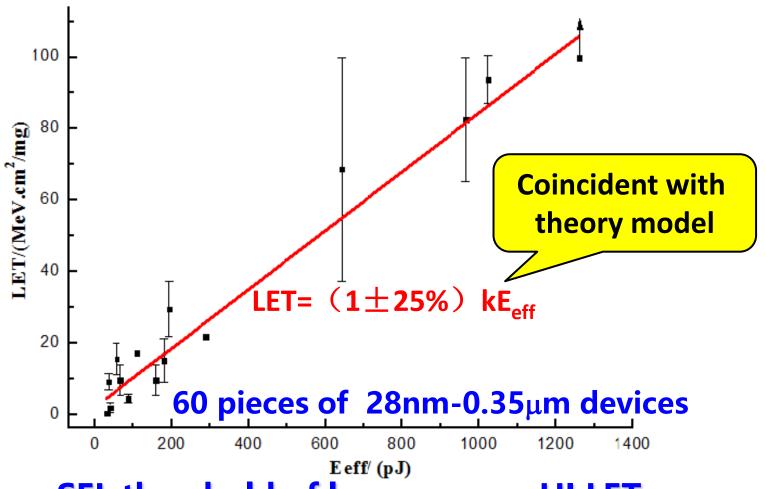
# Nese Pulsed Laser SEE Testing Technique

>Quantitative Calibration





### **✓ SEL Laser Quantitative Calibration**

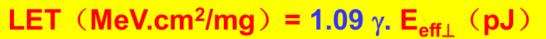


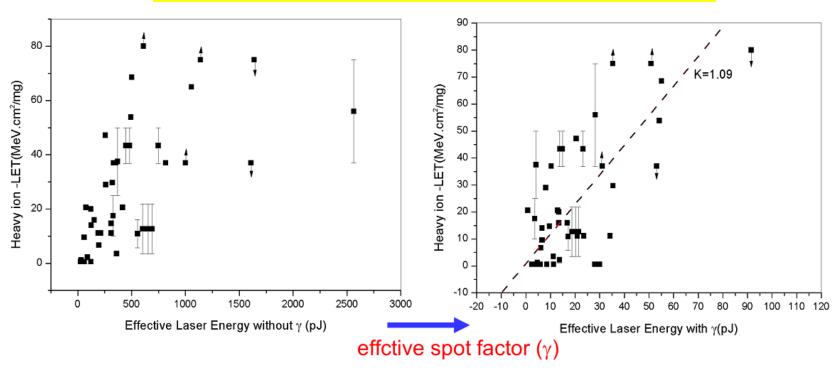
**SEL threshold of laser energy-HI LET** 

[1]Ma Yingqi et al. IEEE NSREC2018.



## **✓ SEU Laser Quantitative Calibration**

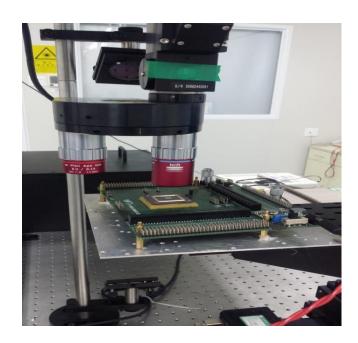


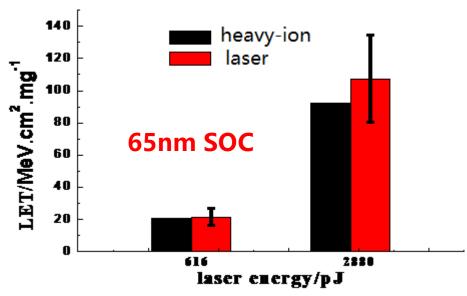


## **SEU threshold of laser energy-HI LET**



#### **✓ SEL Verifacation of Laser Quantitative Calibration**





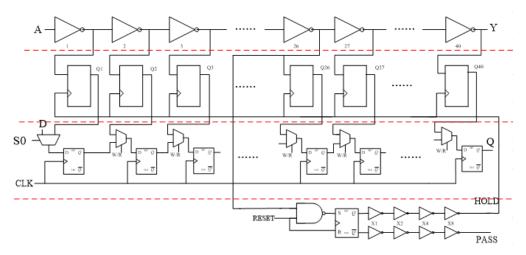
Device	Part Type	Equivalent LET thresholds/	Heavy ion LET thresholds/
		MeV·cm²/mg	MeV·cm²/mg
CAN BUS	Α	12.5±2.7	5.7-17.3
DDS	В	13.7±2.9	5.7-17.3



### **✓ DSET Verifacation of Laser Quantitative Calibration**

#### DUT

bulk silicon CMOS 200-stage inverter chain with SET pulse width for on-chip test is designed.



**SET impulse testing** 

**SET latch circuit** 

Flip-flop test circuit

trigger circuit

#### Facility



Heavy ion	energy /MeV	LET / (MeV·cm²/mg)	lon range / μm
Fe	6.3	29.2	20
Xe	1994.1	49.65	150.44
Xe	1209.5	66	87.88
Ві	1283.3	97.8	69.8

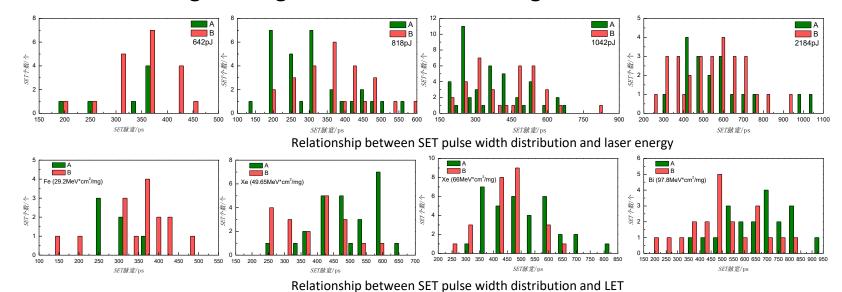
Laser wavelength /nm0	1064
Frequency/Hz	1000
Pulsed width/ps	25
Spot diameter /μm	≈2
fluence	4E6





### **✓ DSET Verification of Laser Quantitative Calibration**

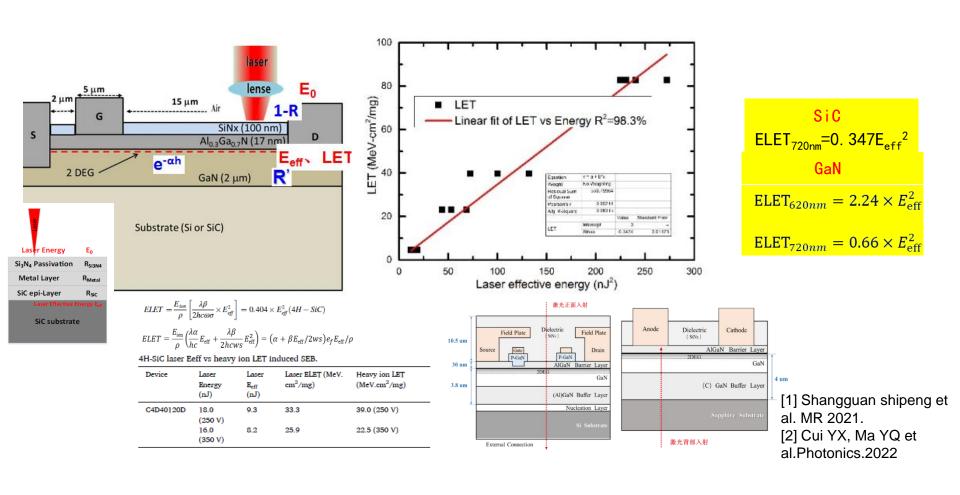
SET pulse width distribution results of different laser energy, heavy ion LET value and PMOS gate length for the combined logic device inverter chain



- □ In double-well CMOS technology, the parasitic bipolar effect and charge sharing effect of PMOS are the main reasons for the double (multiple) peak distribution of SET pulse width at high laser energy and high LET value.
- ☐ The parasitic bipolar transistor effect of PMOS transistor is significant at higher laser energy and LET value, and the parasitic bipolar effect of inverter chain circuit with smaller PMOS gate length is more serious.

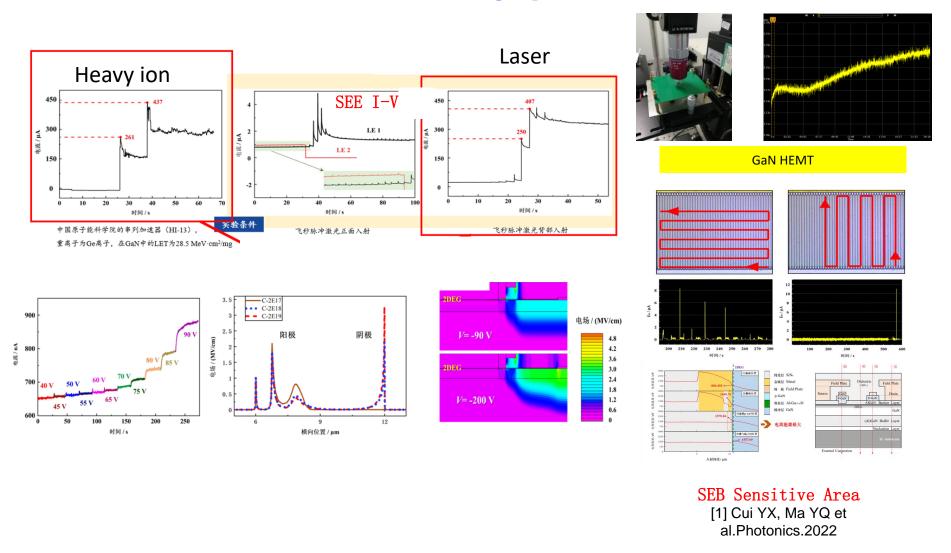


## ✓ SEB of Wide Bandgap Semiconductor Devices for Laser Quantitative Calibration



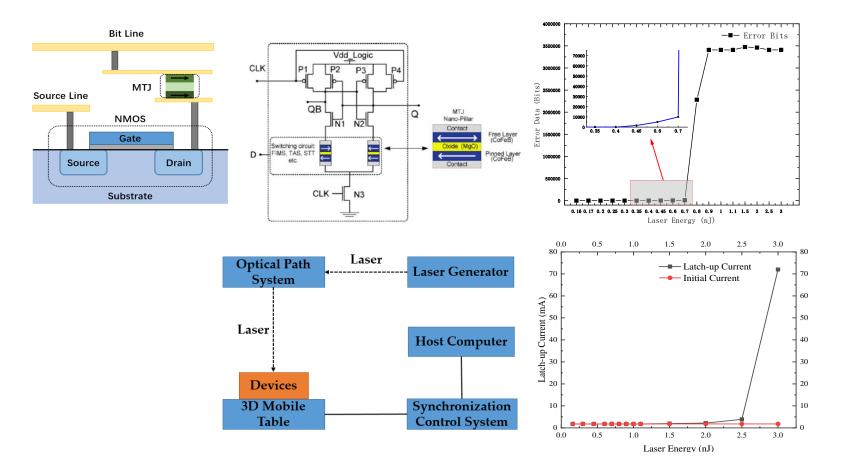


## **✓ SEB Location of Wide Bandgap Semiconductor Devices**



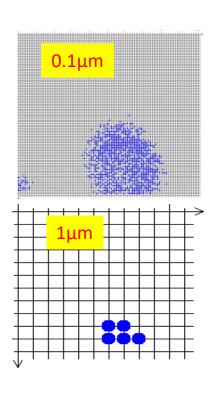


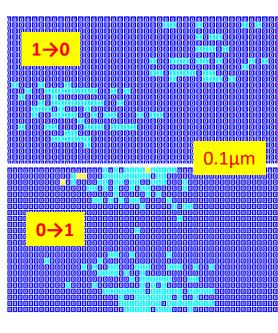
#### **✓ SEFI for MRAM Verification of laser test**





## **✓ SEU Sensitive area location by Laser**





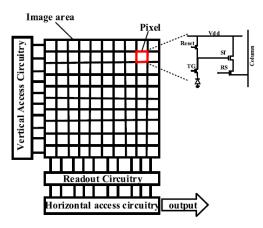
0.1µm

65nm SRAM SEU

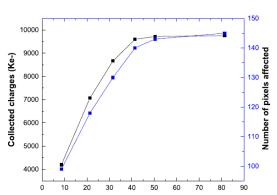
**MCU SRAM** 



## ✓ SET of CMOS Image Sensors(2048(H) × 2048(V))



20000 - 350 pages (Ke) 10000 - 250 and 150 sold | 200 N | 200



LET (MeV·cm²/mg)

(e) (f) (g) (h)

Fig. 3. Pixel clusters captured during pulsed laser irradiation with energies of (a) 150 pJ, (b) 460 pJ, (c) 1130 pJ, (d) 1500 pJ, (e) 2300 pJ, (f) 3000 pJ, (g) 3900 pJ, and (h) 4500 pJ.

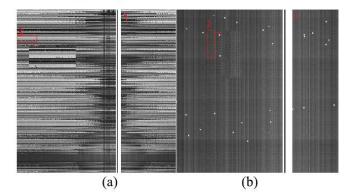


Fig. 5. Image corruption caused by (a) Xe and (b) Br.

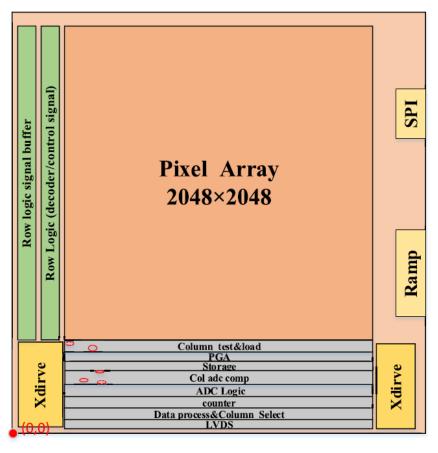
EXPERIMENTAL HEAVY-ION TYPES AND ENERGIES

Accelerator	Ion species	Initial energy(MeV)	LET(MeV cm <sup>2</sup> mg <sup>-1</sup> )	Range(µm(Si))
HIRFL	<sup>181</sup> Ta	1400	81.35	83
	<sup>129</sup> Xe	2000	50.34	150
HI-13	<sup>79</sup> Br	270	41.4	35.5
	<sup>63</sup> Cu	230	31.6	35.5
	<sup>48</sup> Ti	185	21.3	37.9
	<sup>28</sup> Si	156	8.62	60.8

[1]Cai et al. IEEE TNS2020.

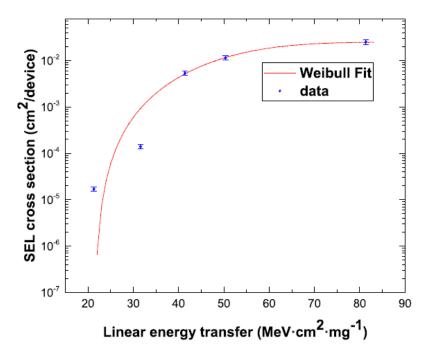


## ✓ SEL of CMOS Image Sensors(2048(H) × 2048(V))



Mapping results by picosecond pulsed laser

[1]Cai et al. IEEE TNS2020.

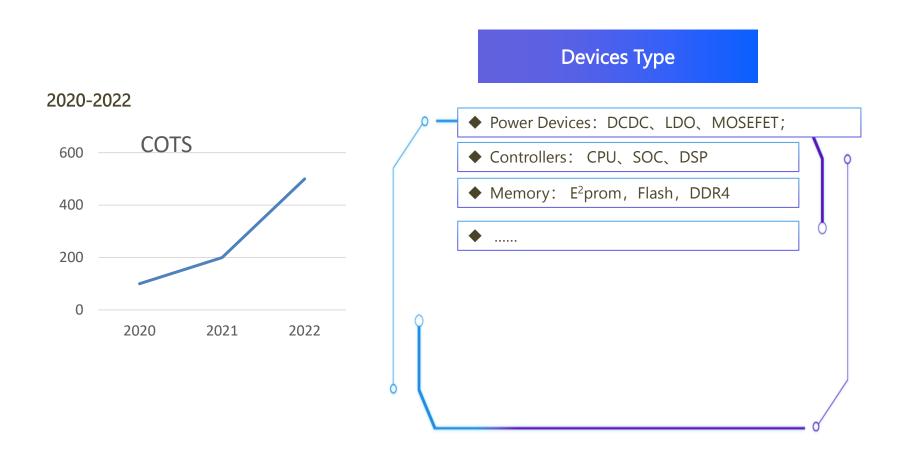


SEL cross section versus LET

For CIS, using pulsed laser mapping tests to measure the number of sensitive volumes is an effective method for calculating space SEL rates.



#### 2020-2022 COTS Devices for Laser test in NSSC





# **Review and Prospect**

#### Now

By theoretical modeling and determination of the key parameters, the laser heavy ion equivalent relationship models for bulk silicon process and wide bandgap semiconductor process devices were obtained, and the above relationship and uncertainty were verified through a series of experiments with single photon and two-photon absorption.

- laser could be an suitable choice with applicable depth of penetration and easier sample preparation.
- Quantitative laser testing is what engineers need.

#### **Next**

Standardization: reliable calibration, repeatability
 How to be equivalent with ground-based accelerator ions and outer-space particles is still an challenging job, especially for the COTS devices.



